

SUBSTITUTE SPECIFICATION
(CLEAN VERSION)

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METHOD FOR PRODUCING AN INTEGRATED CIRCUIT WITH A
REWIRING DEVICE AND CORRESPONDING INTEGRATED CIRCUIT

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CLAIM FOR PRIORITY

This application claims priority to German Application No. 10255844.2 filed November 29, 2002, which is incorporated herein, in its entirety, by reference.

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TECHNICAL FIELD OF THE INVENTION

The present invention relates to a method for producing an integrated circuit with a rewiring device, and a corresponding integrated circuit.

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BACKGROUND OF THE INVENTION

CSPs (chip scale packages) have to date predominantly been constructed on prefabricated substrate strips. In accordance with known CSP technologies based on a substrate, such as Tessera μ BGA (micro ball grid array), for example, the rewiring (redistribution lines) or at least parts thereof are already integrated into the prefabricated substrate. Such a rewiring present on the substrate is then contact-connected by means of bonding wires or TAB bonding to an integrated circuit or a chip. The production of the substrate requires complicated and expensive process steps which increase the costs for the substrate. Furthermore, the production and the subsequent process steps are effected with a low degree of parallelism, e.g. in panels or strips with fewer than 150 chips. Both causes have hitherto prevented a further lowering of the production costs of CSPs. Fan-out rewirings can also be generated by means of CSP technologies based on a substrate, for example by means of the BGA technology.

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